

**$V_{RM} = 200\text{ V}$ ,  $I_{F(AV)} = 10\text{ A}$ ,  $t_{rr} = 30\text{ ns}$**   
**Fast Recovery Diode**  
**SPXS-2102S**

**Description**

The SPXS-2102S is a fast recovery diode of 200 V / 10 A. The maximum  $t_{rr}$  of 30 ns is realized by optimizing a life-time control. The low thermal resistance package achieves high performance in terms of heat dissipation.

**Features**

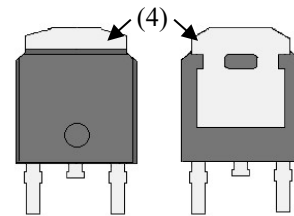
- $V_{RM}$  ----- 200 V
- $I_{F(AV)}$  ----- 10 A
- $V_F$  ----- 1.25 V
- $t_{rr1}$  ----- 30 ns
- Bare Leads: Pb-free (RoHS Compliant)
- Flammability: Equivalent to UL94V-0
- Flow Soldering Available (MSL 1)

**Applications**

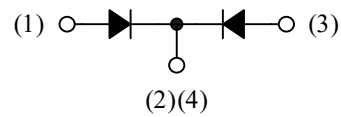
- Secondary-side Rectifier Diode  
(Flyback Converter, LLC Converter, etc.)
- Freewheel Diode  
(Offline Buck Converter, Offline Buck-boost Converter, etc.)

**Package**

TO252-2L



(1) (2) (3)



- (1) Anode  
(2) Cathode  
(3) Anode  
(4) Cathode

Not to scale

## Absolute Maximum Ratings

Unless otherwise specified,  $T_A = 25\text{ }^{\circ}\text{C}$ .

Parameter	Symbol	Conditions	Rating	Unit
Nonrepetitive Peak Reverse Voltage <sup>(1)</sup>	$V_{RSM}$		200	V
Repetitive Peak Reverse Voltage <sup>(1)</sup>	$V_{RM}$		200	V
Average Forward Current	$I_{F(AV)}$	See Figure 3 and Figure 4	10	A
Surge Forward Current <sup>(1)</sup>	$I_{FSM}$	Half cycle sine wave, positive side, 10 ms, 1 shot	65	A
$I^2t$ Limiting Value <sup>(1)</sup>	$I^2t$	$1\text{ ms} \leq t \leq 10\text{ ms}$	21	$\text{A}^2\text{s}$
Junction Temperature	$T_J$		-40 to 150	$^{\circ}\text{C}$
Storage Temperature	$T_{STG}$		-40 to 150	$^{\circ}\text{C}$

## Electrical Characteristics

Unless otherwise specified,  $T_A = 25\text{ }^{\circ}\text{C}$ .

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
Forward Voltage Drop <sup>(1)</sup>	$V_F$	$T_J = 25\text{ }^{\circ}\text{C}$ , $I_F = 5.0\text{ A}$	—	—	1.25	V
		$T_J = 100\text{ }^{\circ}\text{C}$ , $I_F = 5.0\text{ A}$	—	0.82	—	V
Reverse Leakage Current <sup>(1)</sup>	$I_R$	$V_R = V_{RM}$	—	—	50	$\mu\text{A}$
Reverse Leakage Current under High Temperature <sup>(1)</sup>	$H \cdot I_R$	$V_R = V_{RM}$ , $T_J = 150\text{ }^{\circ}\text{C}$	—	—	10	mA
Reverse Recovery Time <sup>(1)</sup>	$t_{rr1}$	$I_F = I_{RP} = 100\text{ mA}$ , 90% recovery point, $T_J = 25\text{ }^{\circ}\text{C}$	—	—	30	ns
	$t_{rr2}$	$I_F = 100\text{ mA}$ , $I_{RP} = 200\text{ mA}$ , 75% recovery point, $T_J = 25\text{ }^{\circ}\text{C}$	—	—	25	ns
Thermal Resistance <sup>(2)</sup>	$R_{th(J-C)}$	<sup>(3)</sup>	—	—	5.0	$^{\circ}\text{C/W}$

## Mechanical Characteristics

Parameter	Conditions	Min.	Typ.	Max.	Unit
Package Weight		—	0.32	—	g

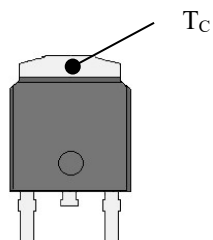


Figure 1. Case Temperature Measurement Point

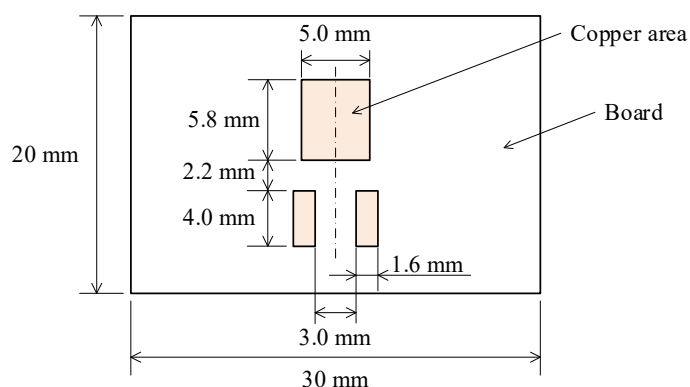


Figure 2. Glass-epoxy Board

<sup>(1)</sup> Specifies a value per chip; the SPXS-2102S consists of two chips.

<sup>(2)</sup> Refers to thermal resistance between junction and the case.

<sup>(3)</sup> The device is mounted on the glass-epoxy board (PCB: 42 mm × 32 mm in size, 1 mm in thickness, copper area: see Figure 2).

## Derating Curves

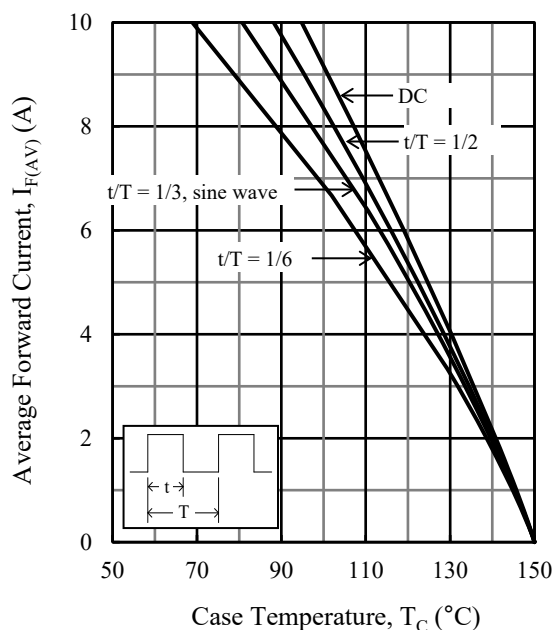


Figure 3.  $I_{F(AV)}$  vs.  $T_C$  ( $T_J = 150$  °C,  $V_R = 0$  V)

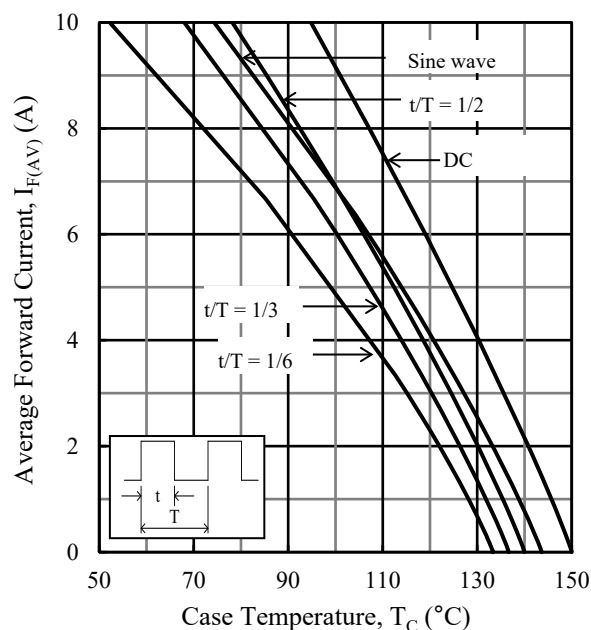


Figure 4.  $I_{F(AV)}$  vs.  $T_C$  ( $T_J = 150$  °C,  $V_R = 200$  V)

## Characteristic Curves

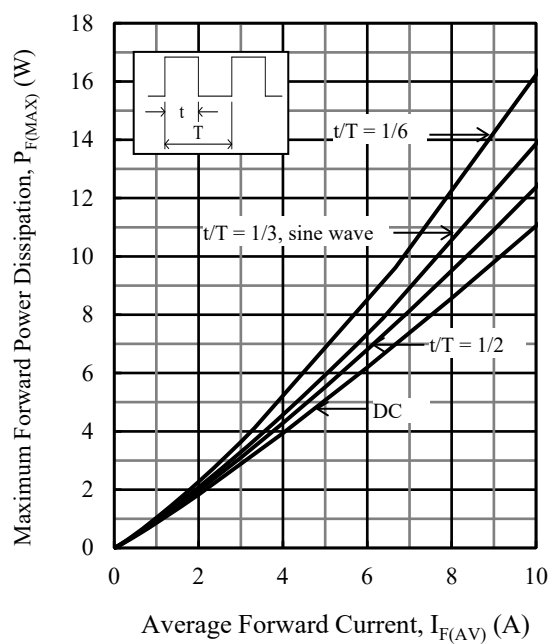


Figure 5.  $P_{F(MAX)}$  vs.  $I_{F(AV)}$  ( $T_J = 150$  °C)

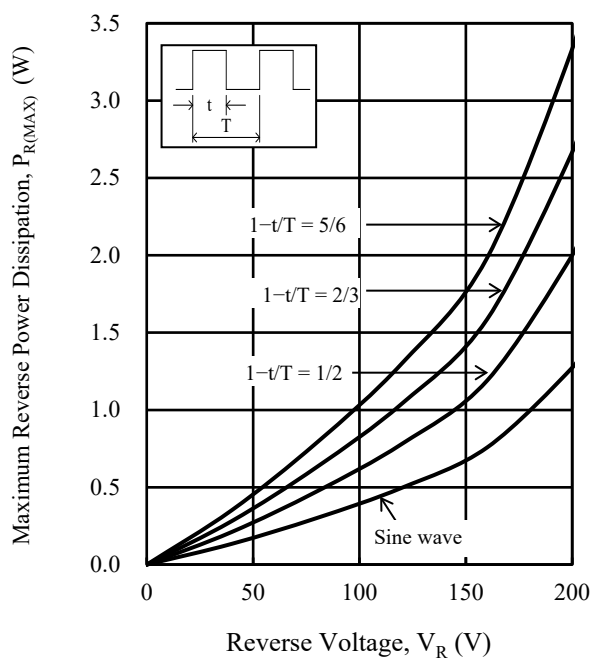


Figure 6.  $P_{R(MAX)}$  vs.  $V_R$  ( $T_J = 150$  °C)

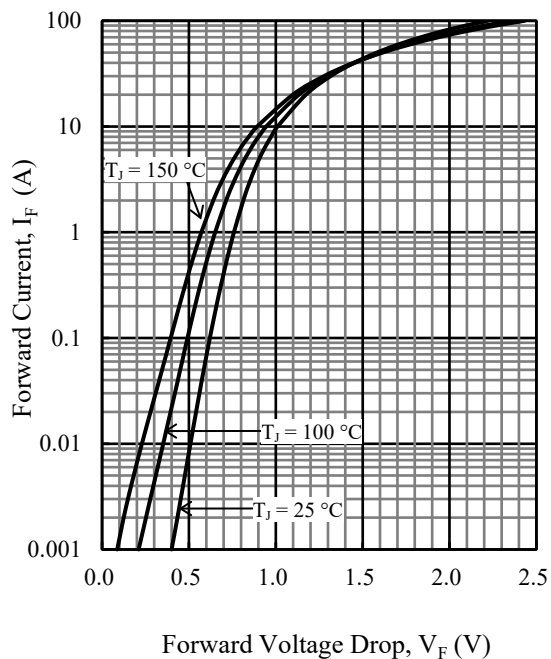


Figure 7. Typical Characteristics:  $I_F$  vs.  $V_F$

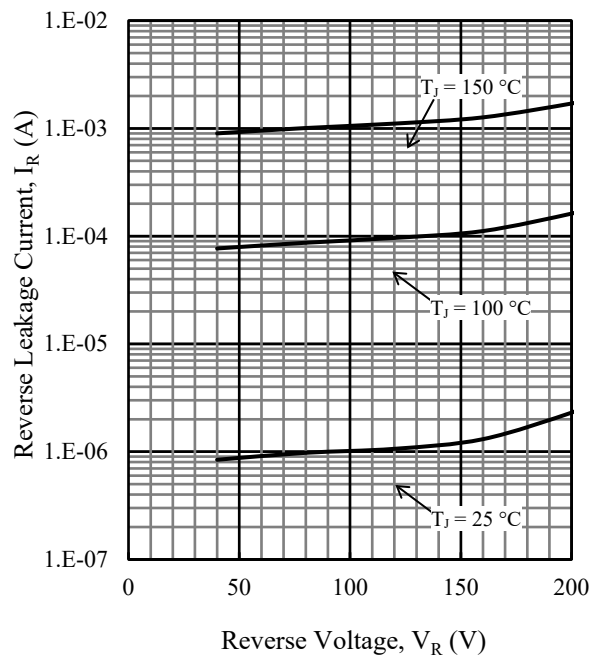


Figure 8. Typical Characteristics:  $I_R$  vs.  $V_R$

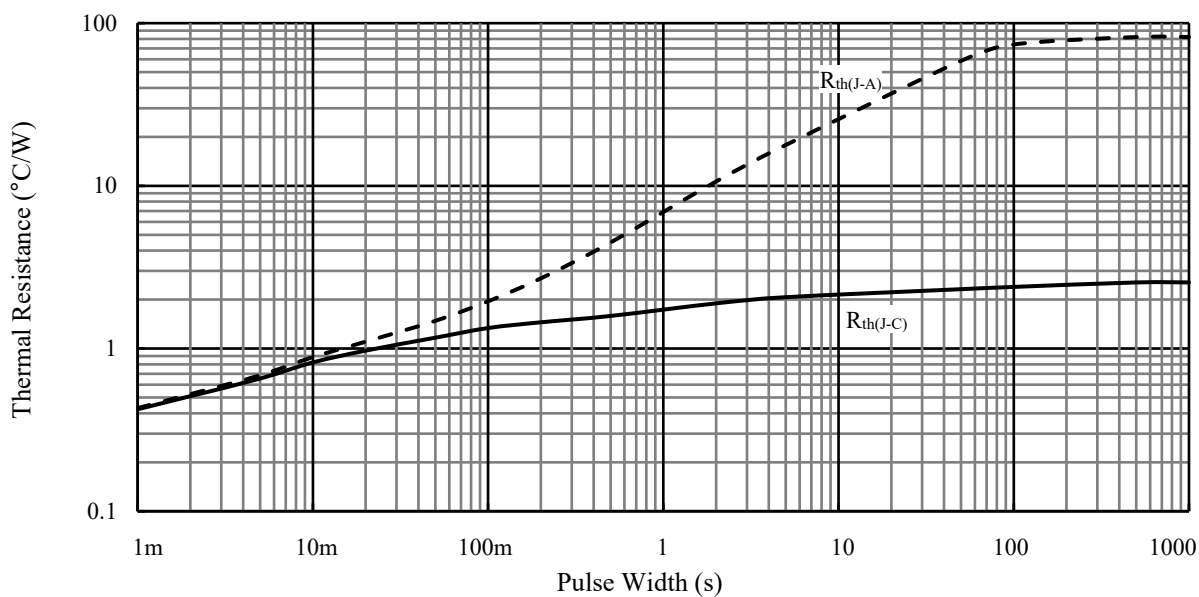
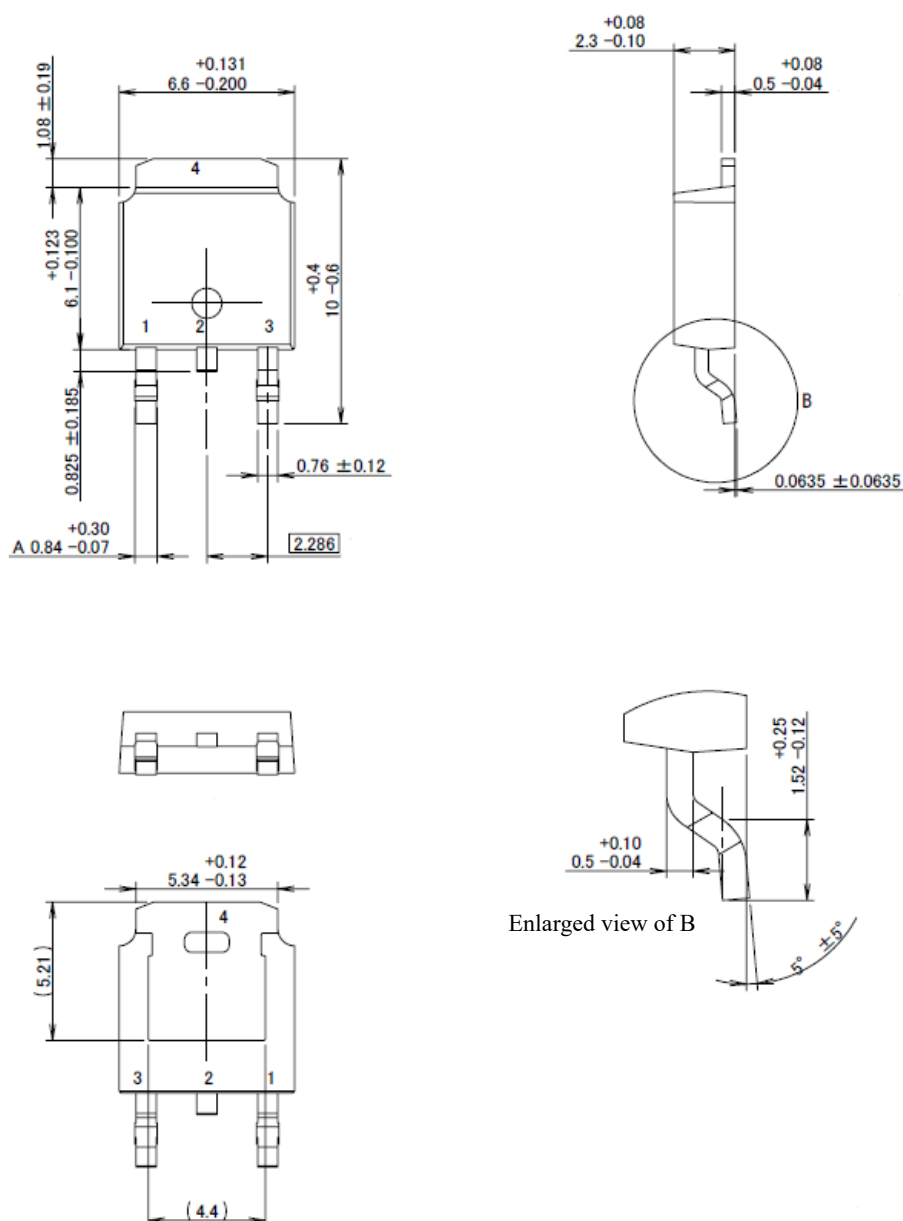


Figure 9. Typical Transient Thermal Resistance Characteristics

# SPXS-2102S

## Physical Dimensions

### • TO252-2L Package

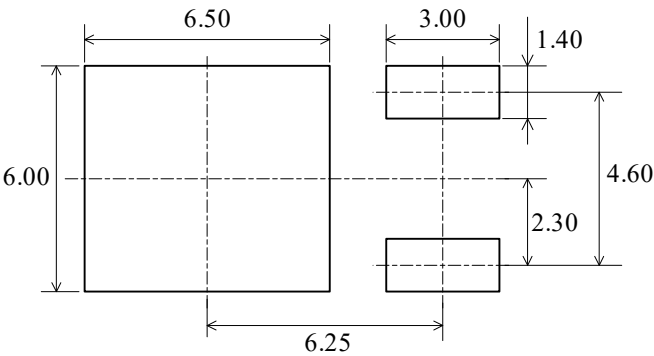


### NOTES:

- Dimensions in millimeters
- All the dimensions exclude mold flashes, protrusions, and gate burrs.
- Bare lead frame: Pb-free (RoHS compliant)
- Moisture Sensitivity Level 1 (MSL 1)
- When soldering the products, it is required to minimize the working time within the following limits:  
 Flow:  $260^\circ\text{C} / 10\text{ s}, 1\text{ time}$   
 Reflow:  
   Preheat:  $150^\circ\text{C}$  to  $200^\circ\text{C} / 60\text{ s}$  to  $120\text{ s}$   
   Solder heating:  $255^\circ\text{C} / 30\text{ s}, 3\text{ times}$  ( $260^\circ\text{C}$  peak)  
   Soldering Iron:  $350^\circ\text{C} / 3.5\text{ s}, 1\text{ time}$

SPXS-2102S

• T0252-2L Land Pattern Example



Dimensions in millimeters

Marking Diagram

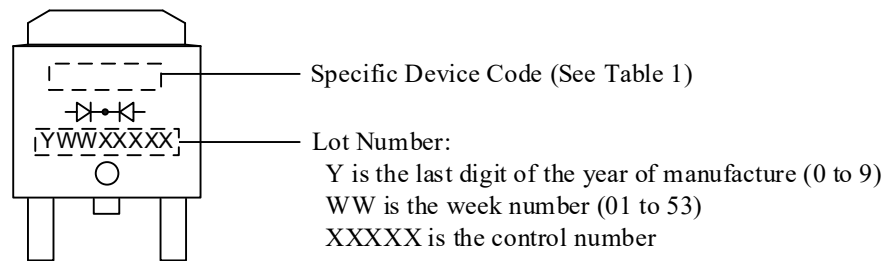


Table 1. Specific Device Code

Specific Device Code	Part Number
XS2102	SPXS-2102S

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